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## Contents

### SESSION 1 ADVANCED FOCAL PLANE ARRAY TECHNOLOGIES I

<table>
<thead>
<tr>
<th>Session</th>
<th>Title</th>
<th>Authors</th>
</tr>
</thead>
<tbody>
<tr>
<td>9100 03</td>
<td>Uncooled microbolometers at DRS and elsewhere through 2013 (Invited Paper) [9100-2]</td>
<td>G. D. Skidmore, C. J. Han, C. Li, DRS Technologies, Inc. (United States)</td>
</tr>
<tr>
<td>9100 04</td>
<td>Performance of PHOTONIS' low light level CMOS imaging sensor for long range observation [9100-3]</td>
<td>L. E. Bourree, PHOTONIS Digital Imaging LLC (United States)</td>
</tr>
<tr>
<td>9100 05</td>
<td>A 33-mpixel 120-fps CMOS image sensor using 0.11-μm CIS process (Invited Paper) [9100-4]</td>
<td>T. Yasue, T. Hayashida, J. Yonai, NHK Japan Broadcasting Corp. (Japan); K. Kitamura, NHK Japan Broadcasting Corp. (Japan) and Shizuoka Univ. (Japan); T. Watabe, NHK Engineering System, Inc. (Japan) and Shizuoka Univ. (Japan); H. Shimamoto, H. Ootake, NHK Japan Broadcasting Corp. (Japan); T. Kosugi, T. Watanabe, S. Aoyama, Brookman Technology, Inc. (Japan); S. Kawahito, Shizuoka Univ. (Japan) and Brookman Technology, Inc. (Japan)</td>
</tr>
</tbody>
</table>

### SESSION 2 ADVANCED FOCAL PLANE ARRAY TECHNOLOGIES II

<table>
<thead>
<tr>
<th>Session</th>
<th>Title</th>
<th>Authors</th>
</tr>
</thead>
<tbody>
<tr>
<td>9100 0B</td>
<td>InAsSb detector and FPA data and analysis (Invited Paper) [9100-10]</td>
<td>A. I. D'Souza, E. Robinson, A. C. Ionescu, D. Okerlund, DRS Sensors &amp; Targeting Systems, Inc. (United States); T. J. De Lyon, R. D. Rajavel, H. Sharifi, HRL Labs., LLC (United States); N. K. Dhar, Defense Advanced Research Projects Agency (United States); P. S. Wijewarnasuriya, U.S. Army Research Lab. (United States); C. Grein, Univ. of Illinois at Chicago (United States)</td>
</tr>
</tbody>
</table>

### SESSION 3 NOVEL TECHNOLOGIES FOR IMAGING

<table>
<thead>
<tr>
<th>Session</th>
<th>Title</th>
<th>Authors</th>
</tr>
</thead>
</table>
Miniaturized imaging spectrometer based on Fabry-Perot MOEMS filters and HgCdTe infrared focal plane arrays (Invited Paper) [9100-14]
S. Velicu, C. Buurma, J. D. Bergeson, EPIR Technologies, Inc. (United States); T. S. Kim, EPIR Technologies, Inc. (United States) and Univ. of California, Santa Cruz (United States); J. Kubby, Univ. of California, Santa Cruz (United States); N. Gupta, U.S. Army Research Lab. (United States)

SESSION 4 SMALL PIXELS AND RELATED TECHNOLOGIES

Recent progress of room temperature THz sources based on nonlinear frequency mixing in quantum cascade lasers (Keynote Paper) [9100-16]
M. Razeghi, Q. Y. Lu, N. Bandyopadhyay, S. Slivken, Y. Bai, Northwestern Univ. (United States)

Case for small pixels: system perspective and FPA challenge (Invited Paper) [9100-17]
J. Robinson, M. Kinch, M. Marquis, D. Littlejohn, K. Jeppson, DRS RSTA, Inc. (United States)

Performance benefits of sub-diffraction sized pixels in imaging sensors (Invited Paper) [9100-18]
J. T. Caulfield, J. A. Wilson, Cyan Systems (United States); N. K. Dhar, Defense Advanced Research Projects Agency (United States)

Effect of dense planer focal plane array on device performances [9100-19]
T. Lin, R. Olah, A. K. Dutta, Banpil Photonics, Inc. (United States)

Enabling more capability within smaller pixels: advanced wafer-level process technologies for integration of focal plane arrays with readout electronics (Invited Paper) [9100-20]
D. S. Temple, E. P. Vick, M. R. Lueck, D. Malta, RTI International (United States); M. R. Skokan, C. M. Masterjohn, M. S. Muzilla, DRS Technologies, Inc. (United States)

Direct optimization of LWIR systems for maximized detection range and minimized size and weight (Invited Paper) [9100-21]
R. Bates, K. Kubala, FoveFocal LLC (United States)

Nanostructured detector technologies for optical sensing applications (Invited Paper) [9100-22]
A. K. Sood, R. E. Welser, Y. R. Puri, Magnolia Optical Technologies, Inc. (United States); N. K. Dhar, Defense Advanced Research Projects Agency (United States); D. L. Polla, Univ. of Minnesota (United States); P. Wijewarnasuriya, M. Dubey, U.S. Army Research Lab. (United States)

POSTER SESSION

Applications of the Lambert W function to analyze digital camera sensors [9100-23]
D. Villegas, Univ. EAFIT (Colombia)
Application of the Ornstein-Uhlenbeck equations for biomedical image processing
J. P. Mesa López, Univ. EAFIT (Colombia)

Improvements to crystal quality of sapphire grown by the Kyropoulos method
J. P. Ciraldo, J. Levine, H. Ganegoda, Rubicon Technology Inc. (United States)

Design of HgCdTe heterojunction photodiodes on Si substrate
P. Zhang, Shanghai Institute of Technical Physics (China) and Univ. of Chinese Academy of Sciences (China); Z. H. Ye, Shanghai Institute of Technical Physics (China); Y. Y. Chen, Shanghai Institute of Technical Physics (China) and Univ. of Chinese Academy of Sciences (China); C. Lin, X. N. Hu, R. J. Ding, L. He, Shanghai Institute of Technical Physics (China)

New approach for underwater imaging and processing
Y. Wen, W. Tian, B. Zheng, G. Zhou, H. Dong, Q. Wu, Qingdao Academy for Opto-Electronics Engineering (China)

Analysis and simulation of a new kind of noise at the input stage of infrared focal plane array
Z. Huang, Y. Chen, S. Huang, J. Fang, Shanghai Institute of Technical Physics (China)

Responsivity performance of extended wavelength InGaAs shortwave infrared detector arrays
T. Li, S. Deng, X. Li, X. Shao, H. Tang, H. Gong, Shanghai Institute of Technical Physics (China)

Image quality assessment of 2-chip color camera in comparison with 1-chip color and 3-chip color cameras in various lighting conditions: initial results
S. Adham Khiabani, Y. Zhang, F. Fathollahi, Univ. of New Brunswick (Canada)

Influence of image compression on the quality of UNB pan-sharpened imagery: a case study with security video image frames
S. Adham Khiabani, Y. Zhang, F. Fathollahi, Univ. of New Brunswick (Canada)

Support for both touch sensing and fingerprint scan with in-cell capacitive LCD
P. Koundinya, X. Zhao, T. Feng, W. Shi, Univ. of Houston (United States)

Performance of near-infrared InGaAs focal plane array with different series resistances to p-InP layer
X. Shao, X. Li, T. Li, Z. Huang, Y. Chen, H. Tang, H. Gong, Shanghai Institute of Technical Physics (China)

Wide dynamic range and high-sensitivity CMOS active pixel sensor using output voltage feedback structure
S.-H. Jo, M. Bae, B.-S. Choi, J. Kim, J.-K. Shin, Kyungpook National Univ. (Korea, Republic of)

Author Index
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1 Advanced Focal Plane Array Technologies I

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**Achyut K. Dutta**, Banpil Photonics, Inc. (United States)
2 Advanced Focal Plane Array Technologies II  
Nibir K. Dhar, Defense Advanced Research Projects Agency  
   (United States) 
Achyut K. Dutta, Banpil Photonics, Inc. (United States) 

3 Novel Technologies for Imaging  
Qiaoqiang Gan, University at Buffalo (United States) 
Achyut K. Dutta, Banpil Photonics, Inc. (United States) 

4 Small Pixels and Related Technologies  
Nibir K. Dhar, Defense Advanced Research Projects Agency  
   (United States) 
Patrick Oduor, Banpil Photonics, Inc. (United States)